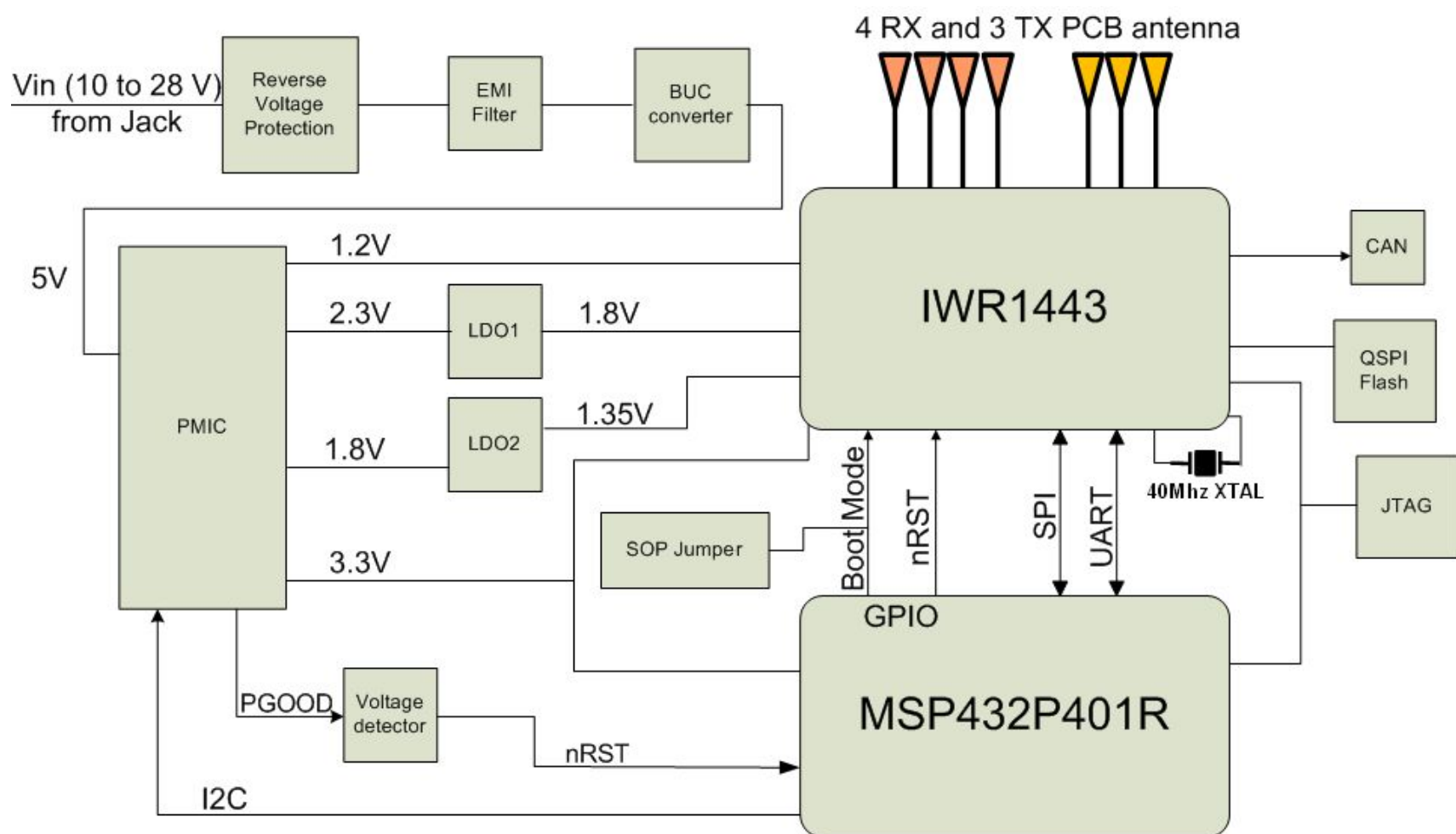
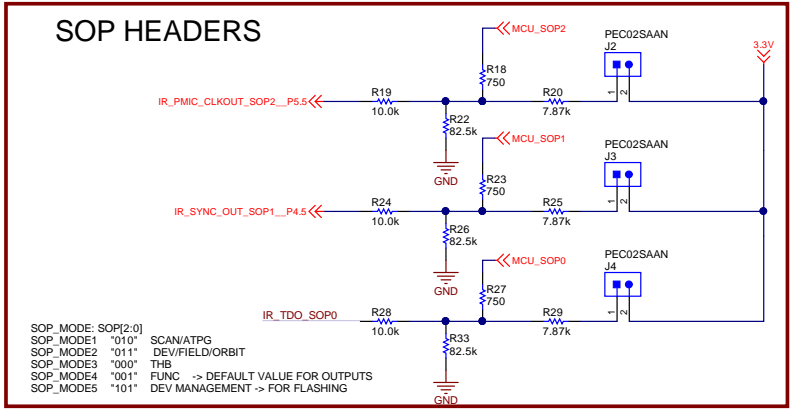
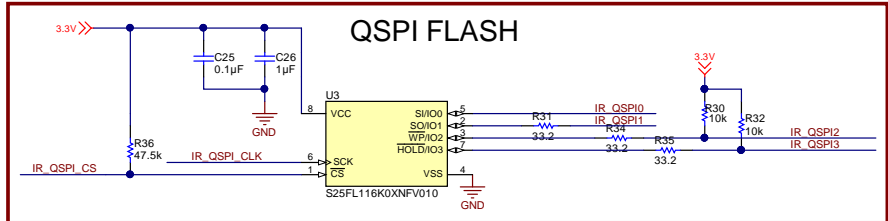
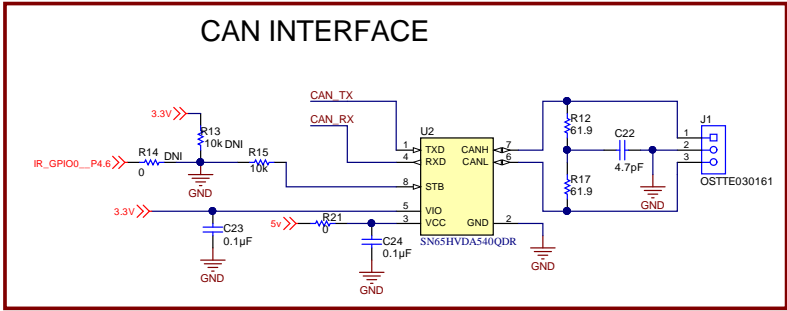
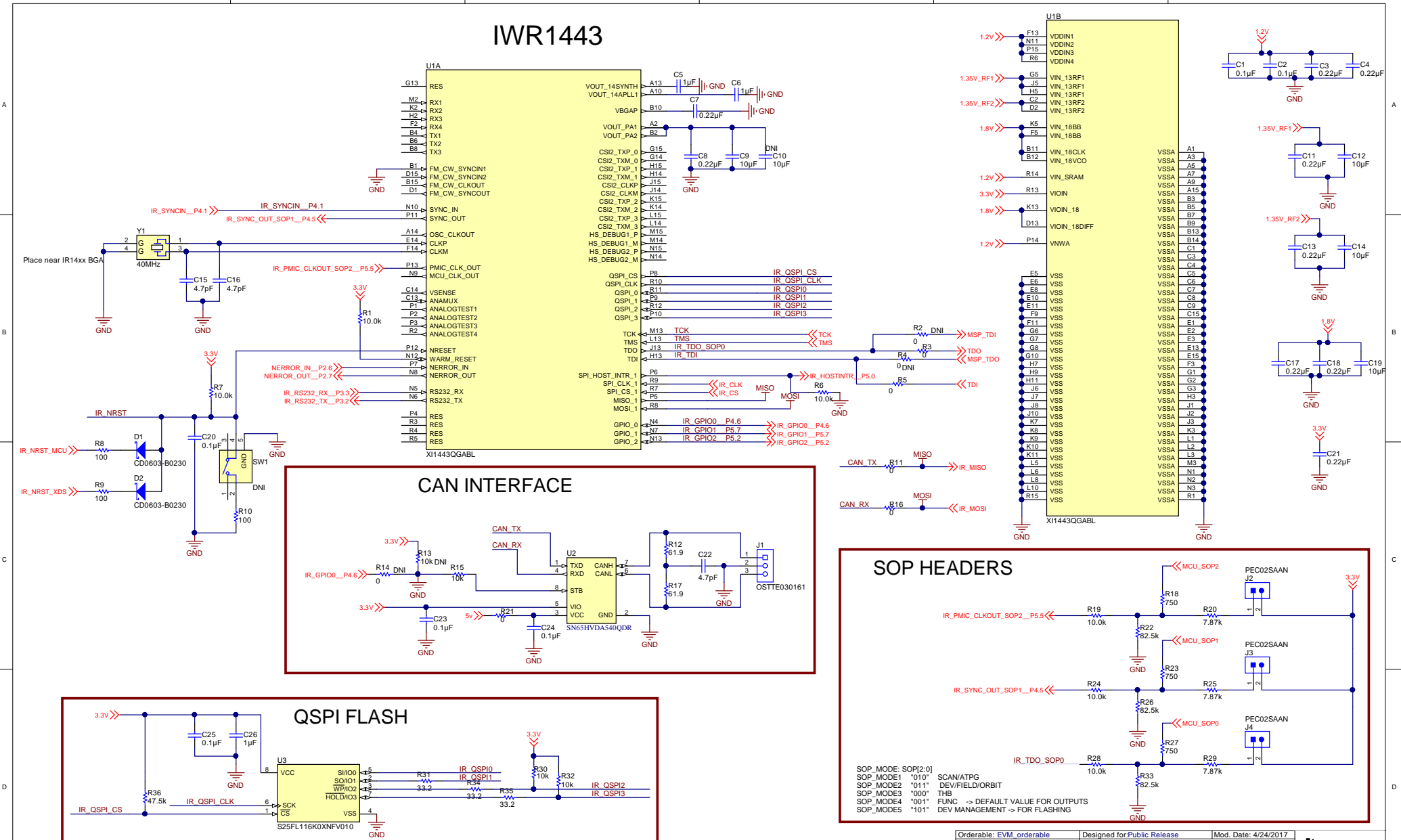


Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
E1	N/A	N/A	N/A	N/A

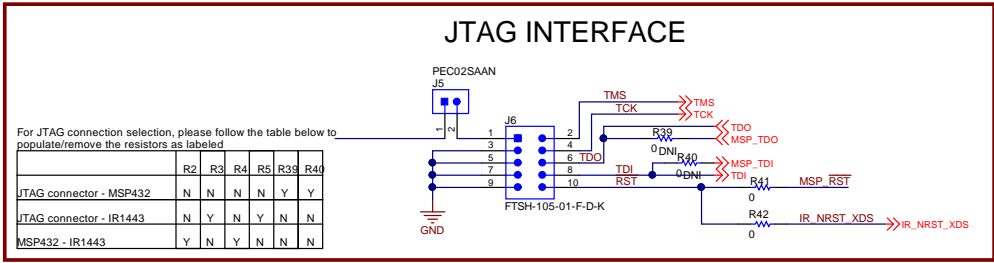
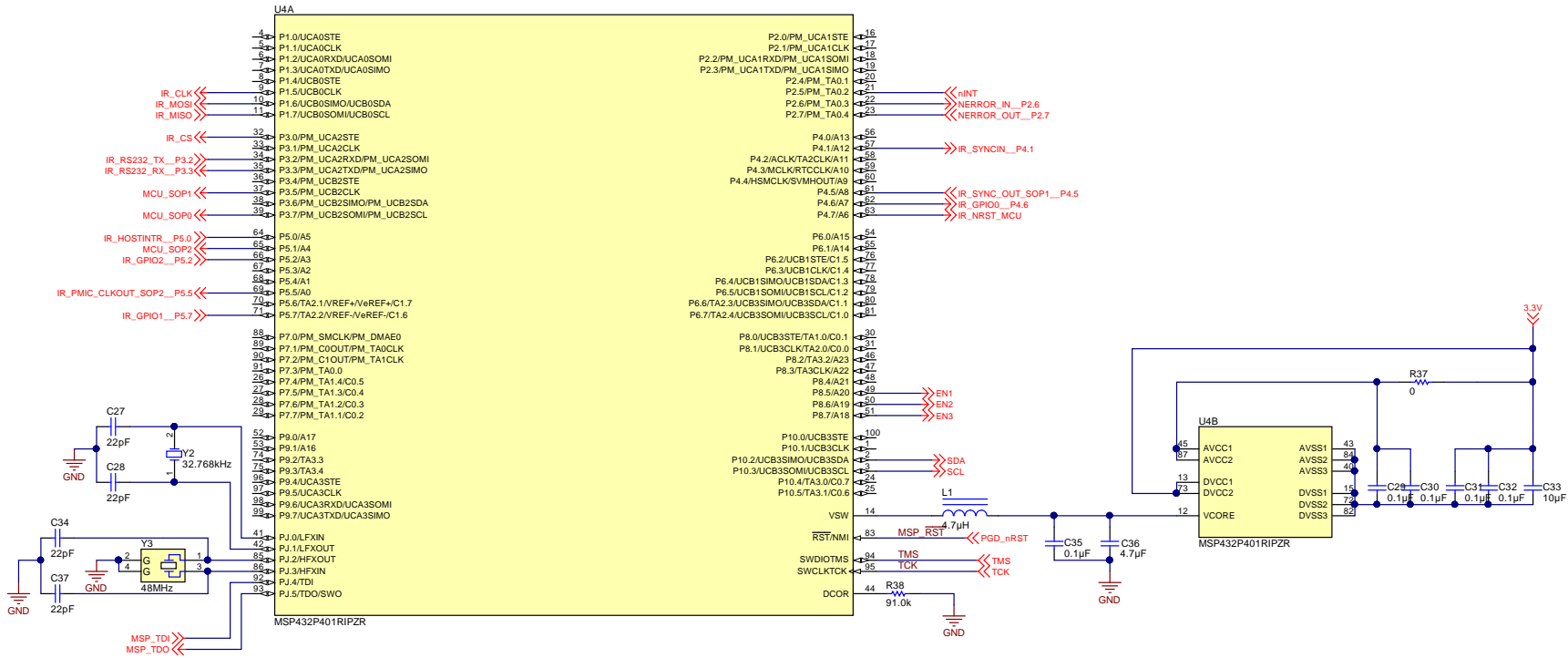


# IWR1443



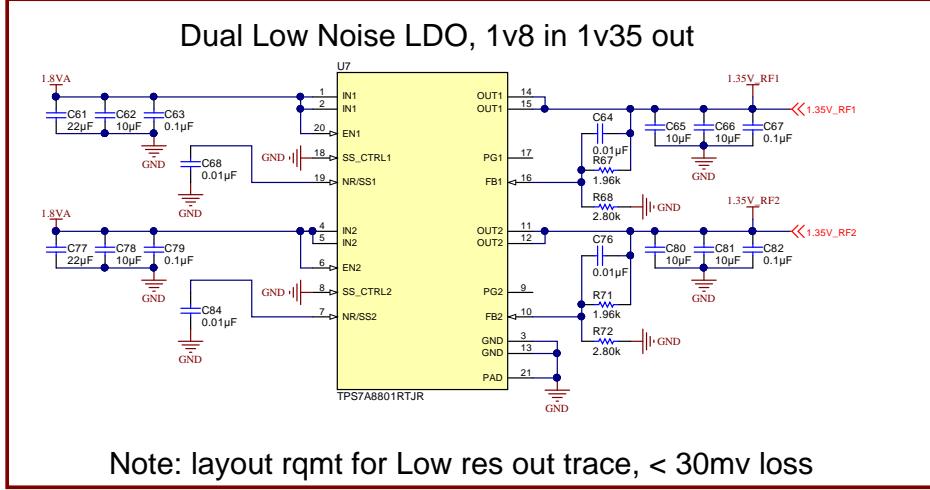
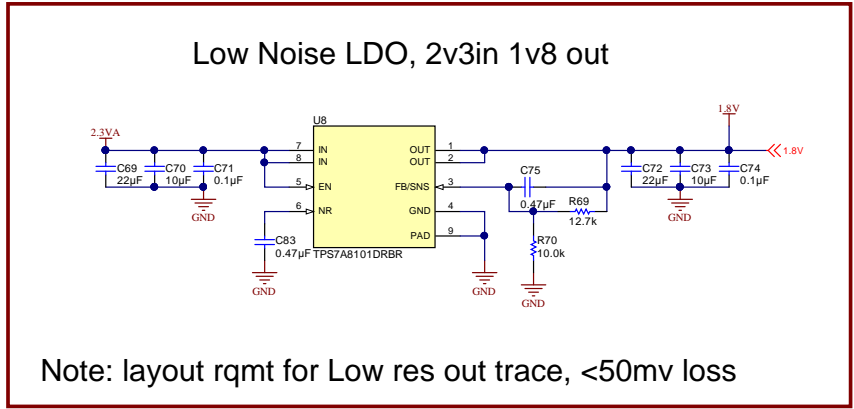
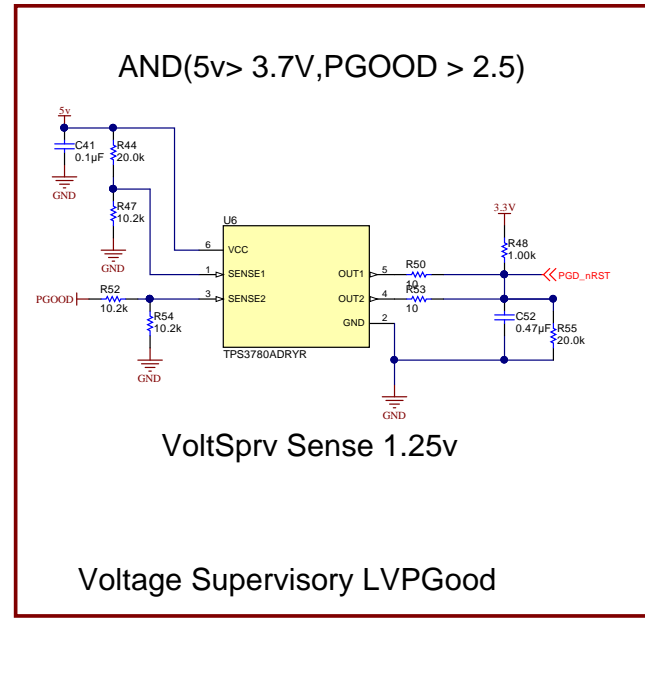
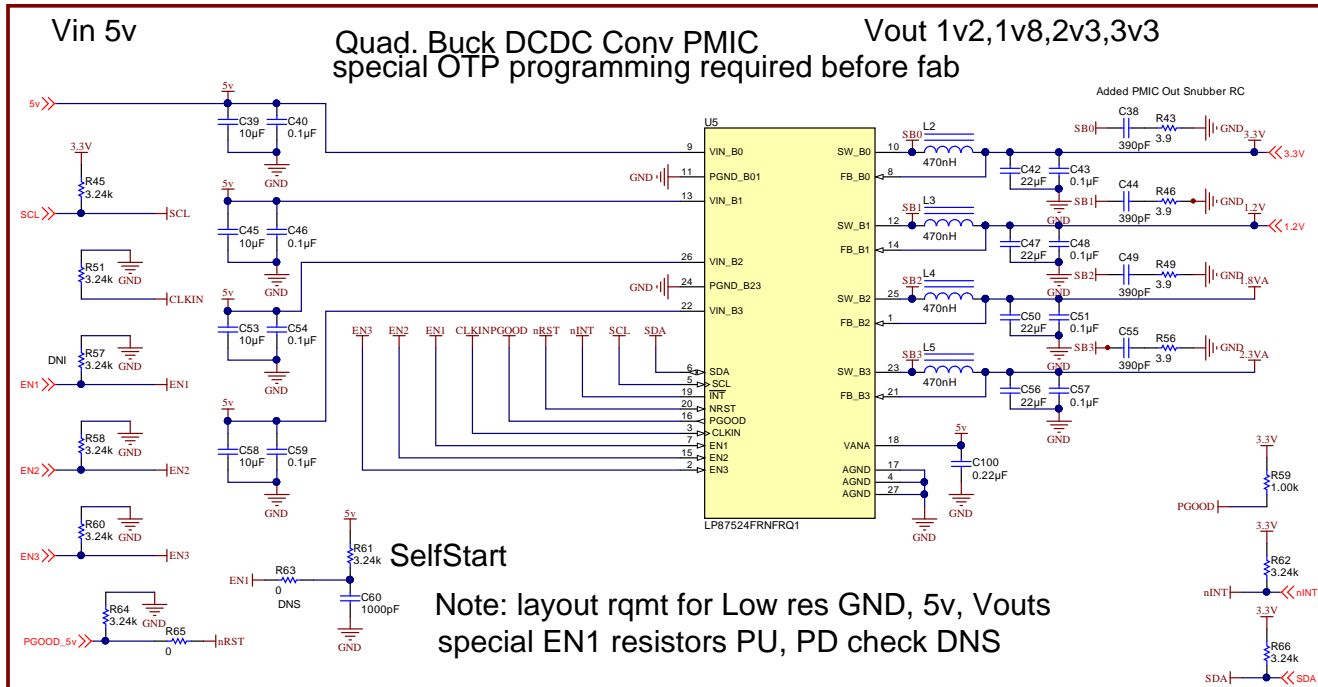
SOP\_MODE1: SOP2[0] SCAN/ATPG  
 SOP\_MODE2: '010' DEV/FIELD/ORBIT  
 SOP\_MODE3: '000' THB  
 SOP\_MODE4: '001' FUNC -> DEFAULT VALUE FOR OUTPUTS  
 SOP\_MODE5: '101' DEV MANAGEMENT -> FOR FLASHING

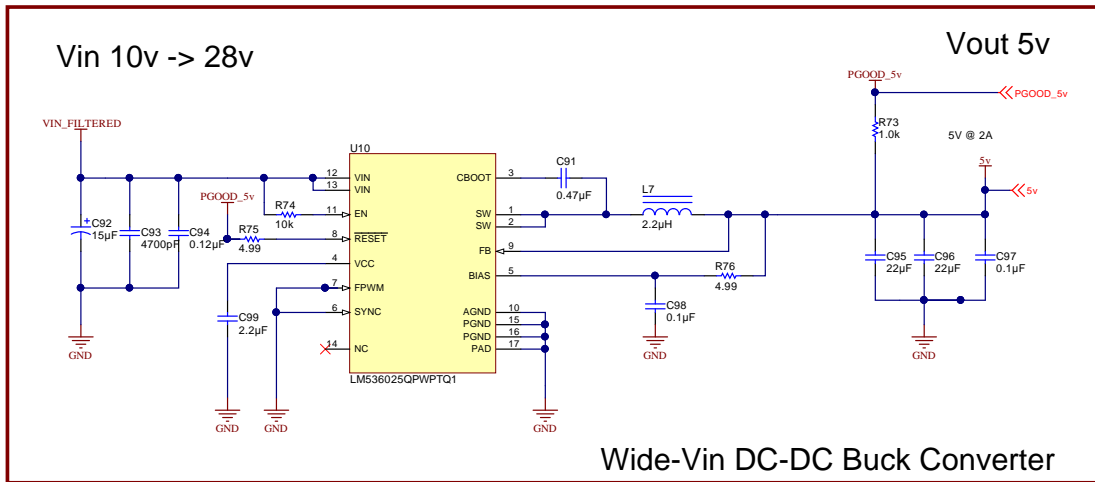
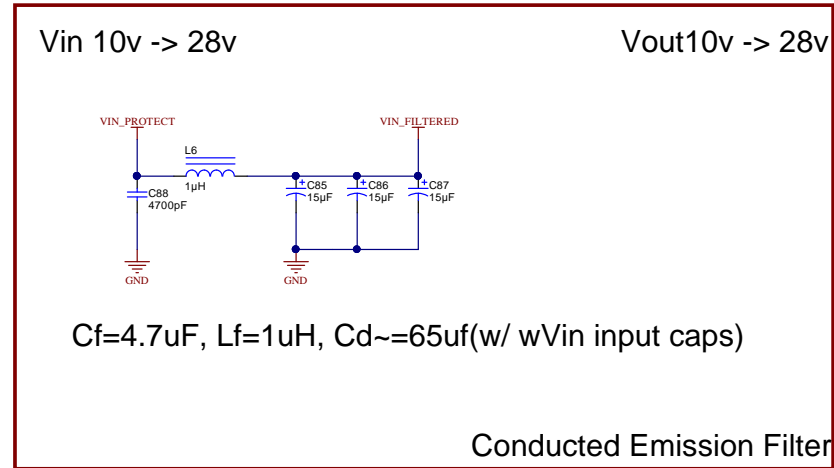
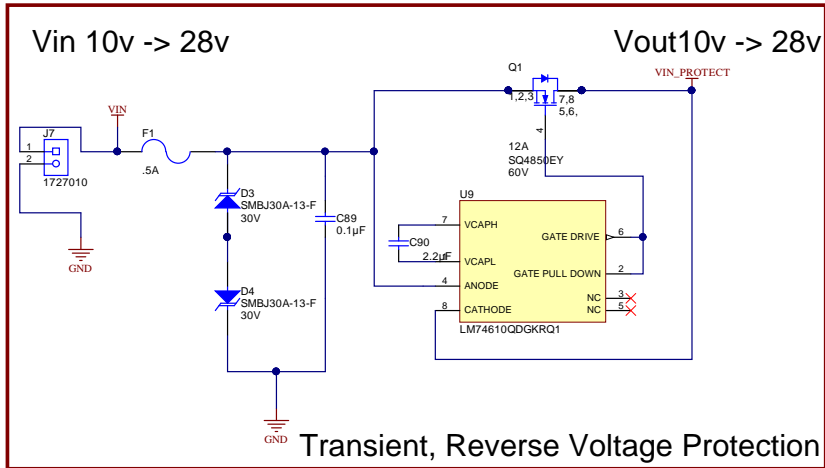
# MSP432P401R



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H1 1 NY PMS 440 0025 PH H2 1 NY PMS 440 0025 PH H3 1 NY PMS 440 0025 PH H4 1 NY PMS 440 0025 PH

H5 1902C H6 1902C H7 1902C H8 1902C

H9 SJ-5303 (CLEAR) H10 SJ-5303 (CLEAR) H11 SJ-5303 (CLEAR) H12 SJ-5303 (CLEAR)

FID1 FID2 FID3 FID4

PCB Number: PCB Rev: E1  
 PCB LOGO Texas Instruments  
 PCB LOGO ESD SENSITIVE  
 PCB LOGO FCC disclaimer

LBL1  
 PCB Label  
 Size: 0.65" x 0.20"

ZZ1  
 Label Assembly Note  
 This Assembly Note is for PCB labels only

ZZ2  
 Assembly Note  
 These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
 Assembly Note  
 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
 Assembly Note  
 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZ5  
 Assembly Note  
 Components marked as "DNI" will not be assembled

Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 4/24/2017
TID #: N/A	Project Title: Design1 with IR1443 and MSP432	
Number: [Rev: E1]	Sheet Title:	Sheet: 6 of 6
Drawn By: [Rev: Version control disabled]	Assembly Variant: [No Variations]	Size: B
Engineer: Michelle Liu	File: Design1_EVM_Hardware.SchDoc	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>

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